# mail

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BFR92AW

NPN 5 GHz wideband transistor

Rev. 03 — 12 March 2008

**Product data sheet** 

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NXP Semiconductors



#### FEATURES

- High power gain
- Gold metallization ensures
   excellent reliability
- SOT323 (S-mini) package.

#### APPLICATIONS

It is designed for use in RF amplifiers, mixers and oscillators with signal frequencies up to 1 GHz.

#### DESCRIPTION

Silicon NPN transistor encapsulated in a plastic SOT323 (S-mini) package. The BFR92AW uses the same crystal as the SOT23 version, BFR92A.

#### PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	

## 3 3 1 2 Top view MBC870

Fig.1 SOT323

Marking code: P2.

#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	-	20	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-	15	V
I <sub>C</sub>	collector current (DC)		-	-	25	mA
P <sub>tot</sub>	total power dissipation	up to $T_s = 93 \text{ °C}$ ; note 1	-	-	300	mW
h <sub>FE</sub>	current gain	I <sub>C</sub> = 15 mA; V <sub>CE</sub> = 10 V	65	90	135	
C <sub>re</sub>	feedback capacitance	$I_{C} = 0; V_{CE} = 10 \text{ V}; f = 1 \text{ MHz};$ $T_{amb} = 25 ^{\circ}\text{C}$	_	0.35	_	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 15 mA; V <sub>CE</sub> = 10 V; f = 500 MHz	3.5	5	-	GHz
G <sub>UM</sub>	maximum unilateral power gain	$I_{C}$ = 15 mA; $V_{CE}$ = 10 V; f = 1 GHz; $T_{amb}$ = 25 °C	-	14	-	dB
		$I_{C}$ = 15 mA; $V_{CE}$ = 10 V; f = 2 GHz; $T_{amb}$ = 25 °C	-	8	-	dB
F	noise figure	$I_{C}$ = 5 mA; $V_{CE}$ = 10 V; f = 1 GHz; $\Gamma_{s} = \Gamma_{opt}$	-	2	-	dB
Tj	junction temperature		-	-	150	°C

#### Note

1.  $T_s$  is the temperature at the soldering point of the collector pin.

#### **Product specification**

### BFR92AW

#### LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

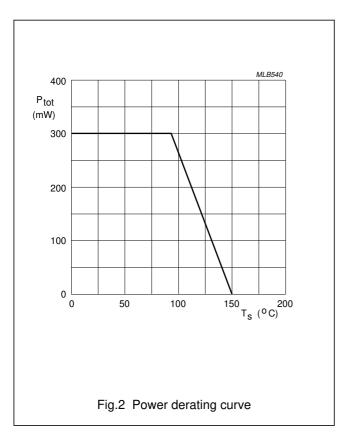
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	20	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	15	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	2	V
I <sub>C</sub>	collector current (DC)		-	25	mA
P <sub>tot</sub>	total power dissipation	up to $T_s = 93 \text{ °C}$ ; see Fig.2; note 1	-	300	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Т <sub>ј</sub>	junction temperature		_	150	°C

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	up to T <sub>s</sub> = 93 °C; note 1	190	K/W

#### Note to the Limiting values and Thermal characteristics

1.  $T_s$  is the temperature at the soldering point of the collector pin.



#### BFR92AW

#### CHARACTERISTICS

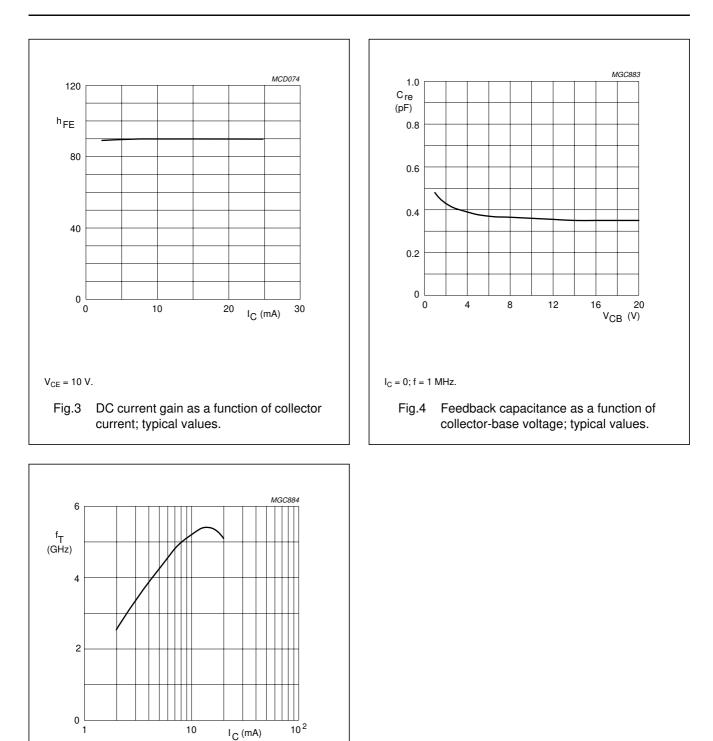
 $T_j = 25 \ ^{\circ}C$  (unless otherwise specified).

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector leakage current	I <sub>E</sub> = 0; V <sub>CB</sub> = 10 V	-	-	50	nA
h <sub>FE</sub>	DC current gain	$I_{C} = 15 \text{ mA}; V_{CE} = 10 \text{ V}$	65	90	135	
C <sub>c</sub>	collector capacitance	I <sub>E</sub> = i <sub>e</sub> = 0; V <sub>CB</sub> = 10 V; f = 1 MHz	-	0.6	-	pF
Ce	emitter capacitance	$I_{C} = i_{c} = 0; V_{EB} = 0.5 V; f = 1 MHz$	-	0.9	-	pF
C <sub>re</sub>	feedback capacitance	$I_{C} = 0; V_{CE} = 10 V; f = 1 MHz$	-	0.35	-	pF
f <sub>T</sub>	transition frequency	$I_{C} = 15 \text{ mA}; V_{CE} = 10 \text{ V}; f = 500 \text{ MHz}$	3.5	5	-	GHz
G <sub>UM</sub>	maximum unilateral power gain; note 1	I <sub>C</sub> = 15 mA; V <sub>CE</sub> = 10 V; f = 1 GHz; T <sub>amb</sub> = 25 °C	-	14	-	dB
		I <sub>C</sub> = 15 mA; V <sub>CE</sub> = 10 V; f = 2 GHz; T <sub>amb</sub> = 25 °C	-	8	-	dB
F	noise figure	$I_{C} = 5 \text{ mA}; V_{CE} = 10 \text{ V};$ f = 1 GHz; $\Gamma_{s} = \Gamma_{opt}$	-	2	-	dB
		$I_{C} = 5 \text{ mA}; V_{CE} = 10 \text{ V};$ f = 2 GHz; $\Gamma_{s} = \Gamma_{opt}$	-	3	-	dB

#### Note

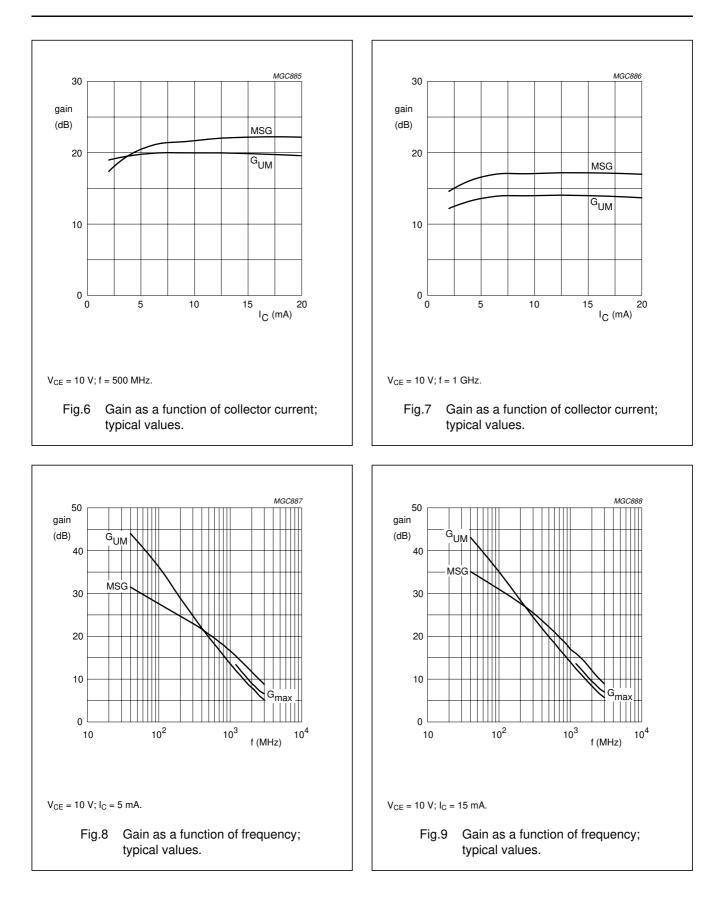
1.  $G_{UM}$  is the maximum unilateral power gain, assuming  $s_{12}$  is zero and  $G_{UM} = 10 \log \frac{|s_{21}|^2}{(1-|s_{11}|^2)(1-|s_{22}|^2)} dB$ .

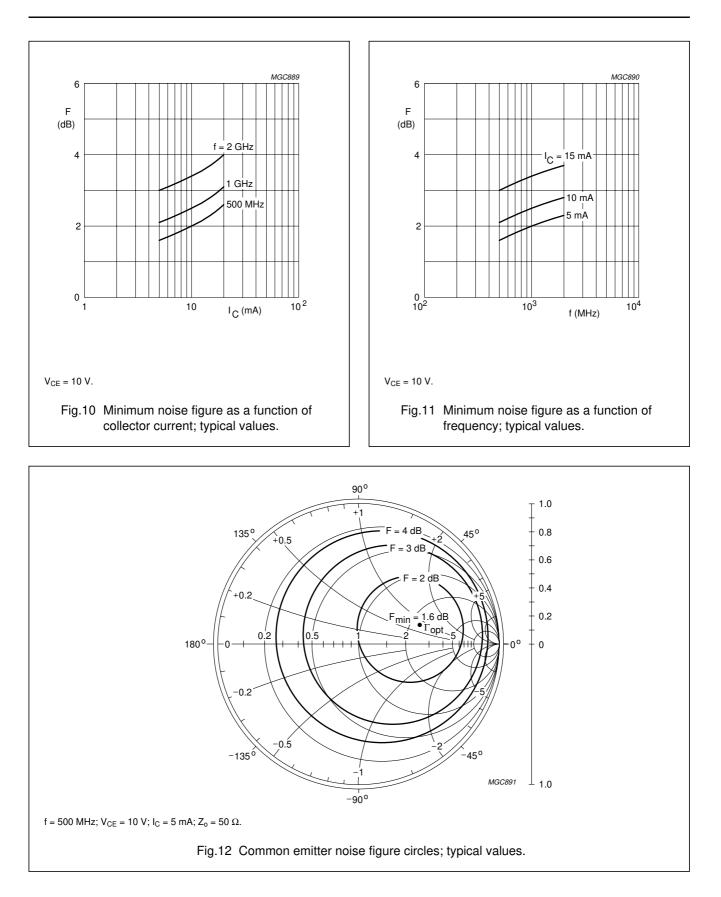
### BFR92AW

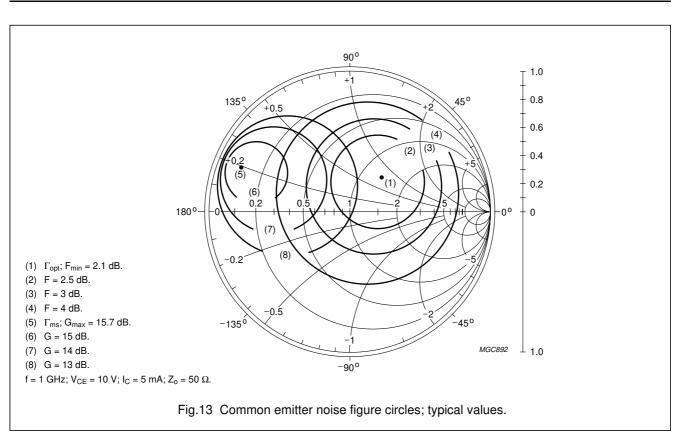


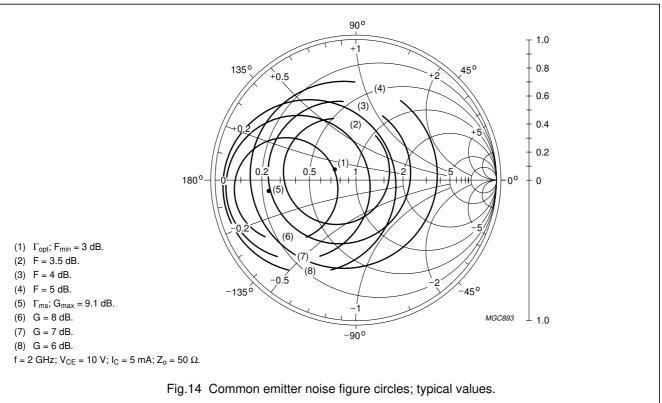
 $V_{CE}$  = 5 V; f = 500 MHz;  $T_{amb}$  = 25 °C.

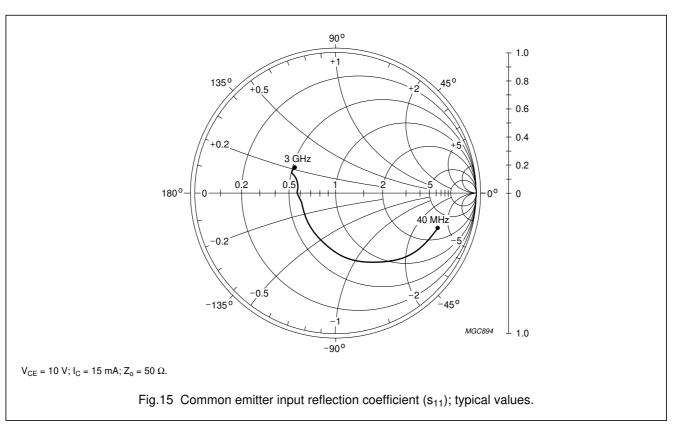
Fig.5 Transition frequency as a function of collector current; typical values.

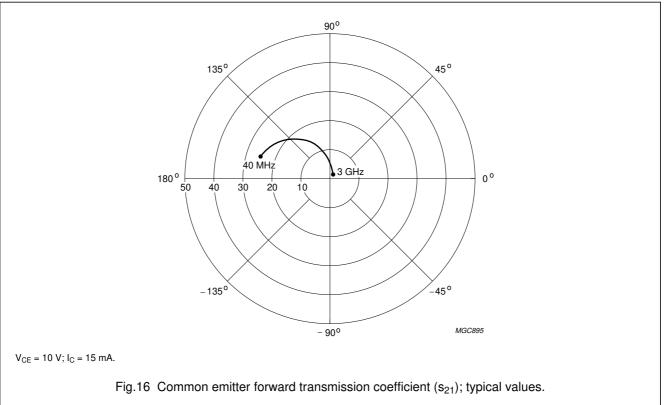


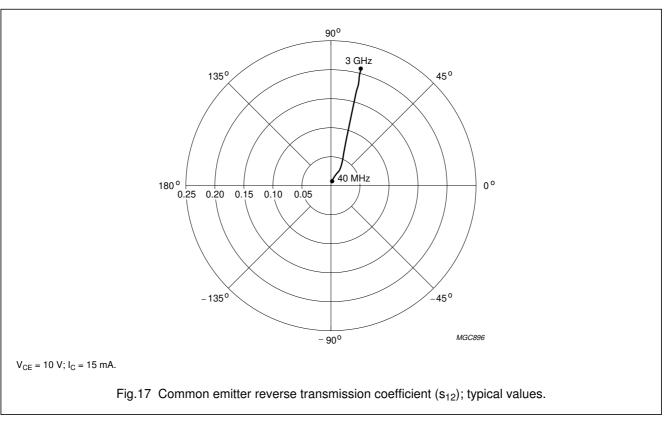


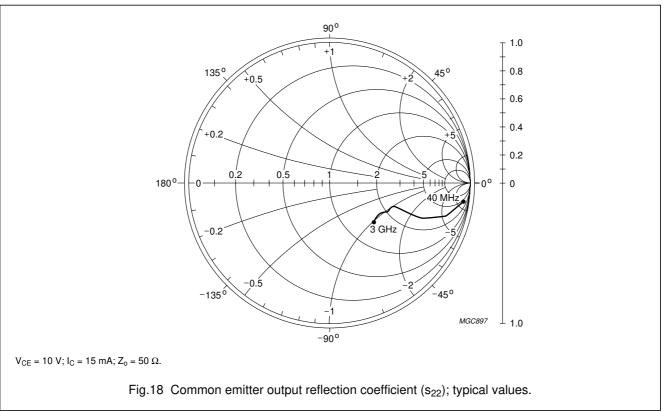






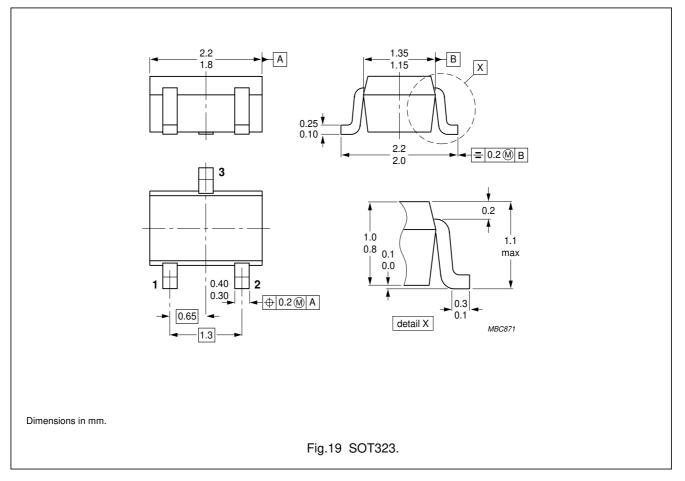






### BFR92AW

#### PACKAGE OUTLINE



### Legal information

#### Data sheet status

Document status[1][2]	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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### **Revision history**

Revision history				
Document ID	Release date	Data sheet status	Change notice	Supersedes
BFR92AW_N_3	20080312	Product data sheet	-	BFR92AW_2
Modifications:	<ul> <li>Quick refere</li> </ul>	ence data and Characteristic	cs Table; DC current ga	in value changed
BFR92AW_2	19950918	Product specification	-	BFR92AW_1
BFR92AW_1	19921001	-	-	-

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Date of release: 12 March 2008 Document identifier: BFR92AW\_N\_3

